



Material Content Data Sheet



Sales Product Name		BSC026NE2LS5		Issued		24. January 2018		
MA#		MA001382824						
Package		PG-TDSON-8-6		Weight*		115.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.231	0.20	0.20	2006	2006
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		128	
	non noble metal	iron	7439-89-6	0.049	0.04		426	
	non noble metal	copper	7440-50-8	49.082	42.53	42.58	425271	425825
	non noble metal	copper	7440-50-8	0.022	0.02	0.02	187	187
wire	non noble metal	copper	7440-50-8	0.022	0.02	0.02	187	187
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		722	
	plastics	epoxy resin	-	5.919	5.13		51290	
	inorganic material	silicondioxide	60676-86-0	35.684	30.92	36.12	309183	361195
leadfinish	non noble metal	tin	7440-31-5	1.452	1.26	1.26	12578	12578
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1434	1434
solder	non noble metal	tin	7440-31-5	0.008	0.01		68	
	noble metal	silver	7440-22-4	0.010	0.01		84	
	non noble metal	lead	7439-92-1	0.372	0.32	0.34	3226	3378
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		58	
	non noble metal	iron	7439-89-6	0.022	0.02		193	
	non noble metal	copper	7440-50-8	22.292	19.31	19.34	193146	193397
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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